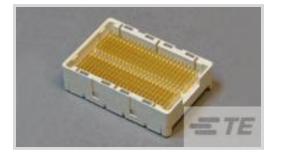
# 6-1761614-0 - ACTIVE

### STEP-Z

TE Internal #: 6-1761614-0 PCB Mount Header, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Partially Shrouded, Gold, Surface Mount -Solder Ball

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 200

Number of Rows: 2

### Features

### Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Partially Shrouded



Sealable	No				
Connector & Contact Terminates To	Printed Circuit Board				
Configuration Features					
Stackable	Yes				
PCB Mount Orientation	Vertical				
Number of Positions	200				
Number of Rows	2				
Board-to-Board Configuration	Parallel				
Electrical Characteristics					
Dielectric Withstanding Voltage (Max)	500 VAC				
Insulation Resistance	18 MΩ				
Operating Voltage	48 VAC				
Body Features					
Primary Product Color	Natural				
Contact Features					

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Contact Layout	Matrix	
Mating Tab Width	1 mm[.04 in]	
Mating Tab Thickness	.2 mm[.008 in]	
Contact Shape & Form	Dual Beam, Single Beam, Square	
PCB Contact Termination Area Plating Material	Tin-Silver	
Contact Base Material	Copper Alloy	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.76 μm[29.9212 μin]	
Contact Type	Tab	
Contact Current Rating (Max)	1 A	
Termination Features		
Termination Method to Printed Circuit Board	Surface Mount - Solder Ball	
Mechanical Attachment		
Mating Retention	With	
Mating Alignment	Without	
PCB Mount Retention	Without	
PCB Mount Alignment	Without	
Connector Mounting Type	Board Mount	
Housing Features		
Centerline (Pitch)	1.3 mm[.051 in]	
Housing Material	Thermoplastic	
Dimensions		
Connector Height	10.95 mm[.43 in]	
Row-to-Row Spacing	2 mm[.079 in]	
Stack Height	15 mm, 21 mm, 25 mm[.984 in]	
PCB Thickness (Recommended)	1.57 mm[.8 in]	
Usage Conditions		
Operating Temperature Range	0-100 °C[32-212 °F]	
Operation/Application		
Assembly Process Feature	None	
Circuit Application	Power & Signal	
Industry Standards		

**C** For support call+1 800 522 6752

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UL Flammability Rating	UL 94V-0				
Packaging Features					
Packaging Quantity	25				
Packaging Type	Tray				
Product Compliance For compliance documentation, visit the product page on TE.com>					
EU RoHS Directive 2011/65/EU	Compliant				
EU ELV Directive 2000/53/EC	Not Yet Reviewed				
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold				
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC				
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free				
Solder Process Capability	Reflow solder capable to 260°C				

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

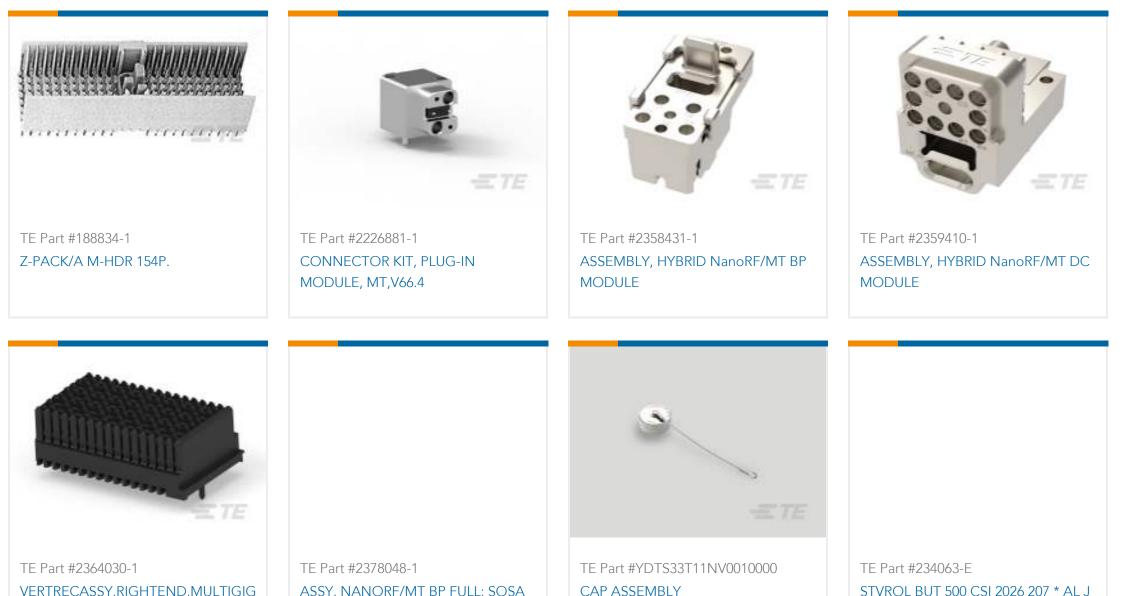


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# Customers Also Bought



RT3(Sn/Pb)	ASSY, NANORF/MIT BP FULL; SOSA 14.26MM	CAPASSEMBLY	2 340
TE Part #374472-E STVTE 160 MI ABCDE VVVVV 4-00 GA06 4,0 *	TE Part #D18310-000 TTVF200RD-100		

### Documents

Product Drawings STEP-Z PLUG 10MM 200P LF ST

English

### **CAD** Files

Customer View Model

### ENG\_CVM\_CVM\_6-1761614-0\_B.2d\_dxf.zip

English

3D PDF

PCB Mount Header, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Partially Shrouded, Gold, Surface Mount - Solder Ball



3D

Customer View Model ENG\_CVM\_CVM\_6-1761614-0\_B.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_6-1761614-0\_B.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages STEP-Z Interconnection System

English

Product Specifications Application Specification

English